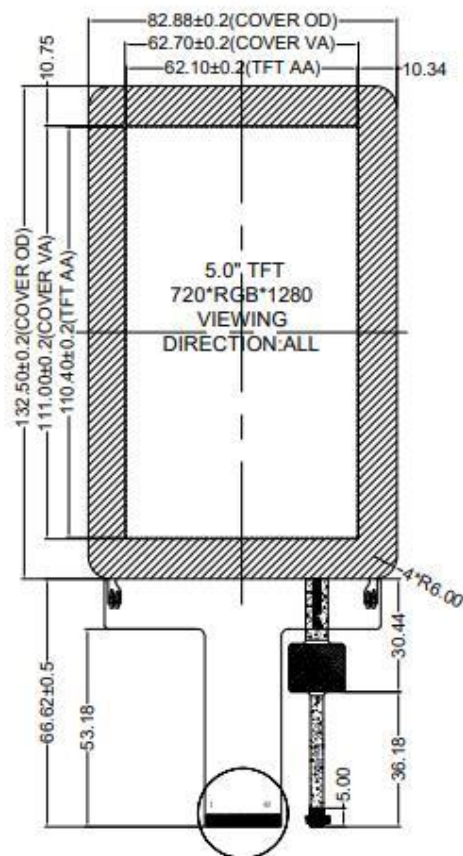
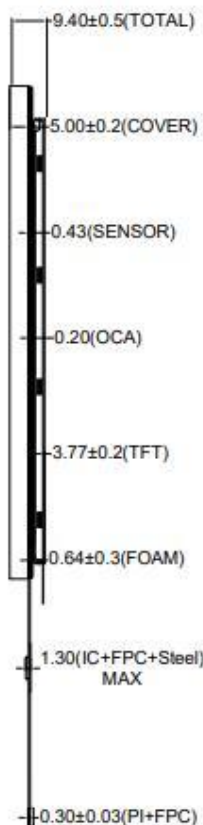


No ROHS hazardous material

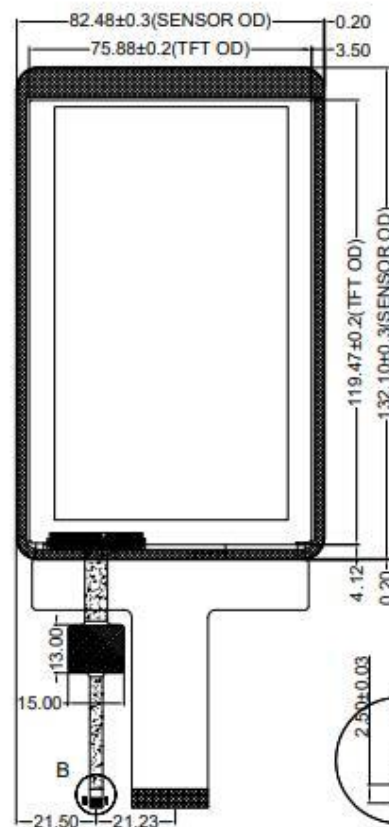
Ordinal	Modify content description	Cartographer	Date of change
△	Add assembly foam glue	LUO	2022-09-06
△			



Front view

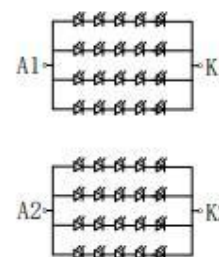


Side view

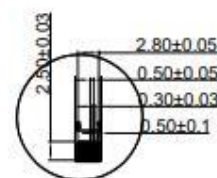


Back view

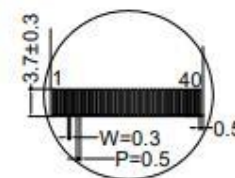
- COVER:BLACK C
- TFT:HX050HI-40M03
- FOAM:3M5925(VHB)



(CIRCUIT DIAGRAM)
VF=30V(TYP) IF=120mA



DETAIL "B"
2:1



DETAIL "A"
2:1

LCD interface	
Pad No.	Pad Name
1	GND
2	D0P
3	D0N
4	GND
5	D1P
6	D1N
7	GND
8	CLKP
9	CLKN
10	GND
11	D2P
12	D2N
13	GND
14	D3P
15	D3N
16	GND
17	GND
18	10VCC 1VB
19	10VCC 1VB
20	NC
21	NC
22	NC
23	NC
24	LCM REST
25	NC
26	NC
27	GND
28	LEDK
29	LEDK
30	LEDK
31	LEDK
32	NC
33	NC
34	LEDA
35	LEDA
36	LEDA
37	GND
38	VDD 3V3
39	VDD 3V3
40	NC

TP Technical Parameters			
1. Interfaces:	I2C	7. Humidity range:	45~85%RH
2. Structure :	G+FPC+TFT(optical bonding)	8. Transmittance:	≥87%
3. IC solutions:	CYTMA568	9. Surface hardness:	≥6H
4. Impact resistance:	IK9	10. Operate :	-20℃~+70℃, ≤85%RH
5. Touch points:	10 points	11. Storage :	-30℃~+80℃, ≤85%RH
6. Power supply:	3.3V (TP)	12. Unmarked dimension tolerance	as ±0.3

IIC	PIN
1	RST
2	VCC3.3V
3	GND
4	INT3.3V
5	SDA3.3V
6	SCL3.3V



杭州宏巢科技有限公司
Grahowlet Technology CO., Ltd

Model	HX0501831			view direction		Unit	MM
Version	V2.0	Designer	LUO	Date	2022-08-02	Edition	A1
Customer		Approved		Date		Proportion	1:1